Filename: PMP8505 REV_A_bom.xls
Date: 10/25/2012

PMP8505 REV_A BOM

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C3	0.047uF	Capacitor, Ceramic, 630V, X7R, 20%	1210	C3225X7R2J473M	TDK
1	C4	330pF	Capacitor, Ceramic, 630V, C0G, NP0, ±5%	1206	Std	Std
1	C8	680uF	Capacitor, Aluminum, 16V, 105C, 20%	0.315 inch	EKZM160ELL681MH15D	Nippon Chemi-Con
1	C11	470pF	CAP 250VAC CERAMIC Y2/X1	0.236 x 0.315 inch	ECK-NVS471KB	Panasonic
1	C12	10pF	Capacitor, Ceramic, 50V, C0G, 10%	0603	STD	STD
1	C14	47uF	Capacitor, Aluminum, SM, ±20%, 35V,	D Code	EEEFK1V470P	Panasonic
1	C16	1nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C17	1000pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C100	0.047uF	Capacitor, Ceramic, 16V, X7R, 10%	0603	Std	Std
2	C1-2	6.8uF	Capacitor, Aluminum, 450V, 105C, 20%	0.315 inch	EKXJ451ELL6R8MJ16S	Nippon Chemi-Con
3	C5-7	22uF	Capacitor, Ceramic, 16V, X7R, 20%	1210	C3225X7R1C226M	TDK
3	C9 C13 C15	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H104K	TDK
1	D1	RH06-T	Diode, Bridge, 0.5-A, 600-V	MiniDIP	RH06-T	Diodes
1	D3	US1K	Diode, Rectifier, 1A, 800V	SMA	US1K	Diodes
1	D4	BAS21	Diode, Switching, 200-mA, 200-V, 330-mW	SOT23	BAS21	Zetex
1	D5	MBR0520L	Diode, Schottky, 0.5A, 20V	SOD-123	MBR0520L	Fairchild
1	D100	20V	Diode, Zener, 20-V, 350-mW	SOT-23	BZX84C20LT1	ON Semi
1	D101	MBRS3100T3	Diode, Schottky 3-A 100-V	SMC	MBRS3100T3	On Semi
1	L1	1000 uH	Inductor, Radial, 0.25A, 6 Ohm	6mm x 8.5mm	7447462102	WE
1	L2	1.2uH	Inductor, SMT, 5.3A, 17milliohm	0.235 x 0.380	DO1813HC-122ML	Coilcraft
1	Q5	SPD02N80C3	MOSFET, N-ch, 800V, 2-A, 2.7 ohm	DPAK	SPD02N80C3	Infineon
1	R1	2.2	Resistor, Chip, 1/16W, 5%	0805	Std	Std
1	R2	100	Resistor, Chip, 1/10W, 5%	0805	CRCW0805-xxx-J	Vishay
1	R3	220K	Resistor, Chip, 1/2W, 1%	2010	Std	Vishay
1	R5	4.7	Resistor, Fusible Power, 1W	0.300 X 0.100 inch	NFR0100004708JR500	Vishay
1	R11	169k	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	R12	10	Resistor, Chip, 1/16W, 5%	0805	Std	Std
1	R13	61.9k	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	R16	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R17	4.75k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R18	100k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R19	20k	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	R21	26.1k	Resistor, Chip, 1/16W, 1%	0603	Std	Std

1	R102	1k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
3	R14-15 R20	100k	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
2	R4 R6	3MEG	Resistor,1/4 watt, 5%	1206	Std	Std
1	T2	800uH	Transformer, Flyback	0.840 x 1.150 inch	SP-EFD 20 Rel. 184281-d	Kaschke
1	TP1	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	TP4	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
3	TP2-3 TP5	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone
1	U1	UCC28610D	IC, Flyback Green-Mode Controller	SO8	UCC28610D	TI
1	U2	TCMT1107	IC, Photocoupler	MF4	TCMT1107	Vishay
1	U3	TL432A	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL432AIDBZR	TI

Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
2. These assemblies must be clean and free from flux and all contaminants.
   Use of no clean flux is not acceptable.
3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
4. Ref designators marked with an asterisk ('**') cannot be substituted.
   All other components can be substituted with equivalent MFG's components.

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